

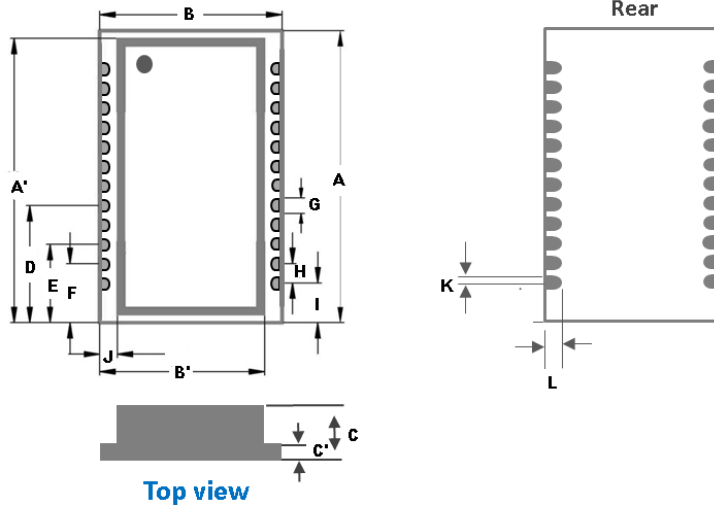
1. Part No. Expression:

SLT161040G241P1B8

(a) (b) (c) (d)(e)(f) (g)

- a) Series Code
- b) Dimension Code
- c) Application Code
- d) Pin Code
- e) Center Tab
- f) Pitch
- g) Special Code

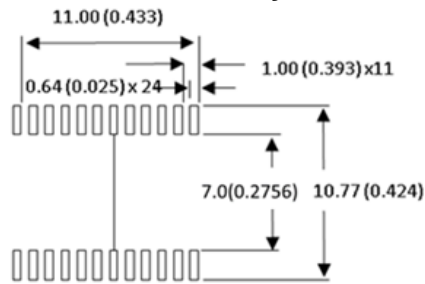
2. Configuration & Dimensions:



Unit: mm

A	A'	B	B'	C	C'	D	E	F
16.5±0.25	16.0±0.25	10.3±0.25	9.65±0.25	4.1±0.25	0.8±0.05	6.75±0.25	4.75±0.25	3.75±0.25
G	H	I	J	K	L			
0.40±0.05	1.0±0.25	2.75±0.25	0.65±0.05	0.20±0.05	1.0±0.25			

3. PCB Pad & Pin layout:

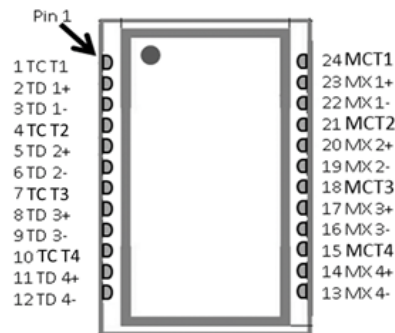


Measurement format: mm/inch

Tolerance: mm (inch) Tolerance: XX.X0 +/-0.25 (0.010)

0.XX +/-0.05 (0.002)

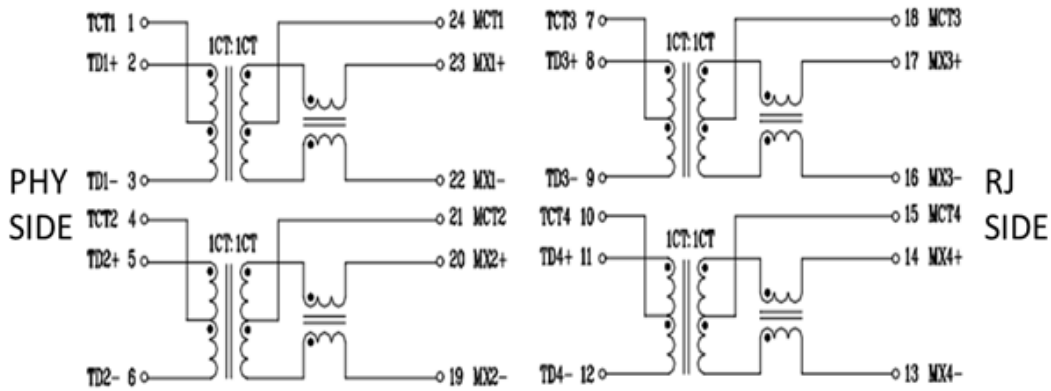
*All tolerance with reference to mm measurements



NOTE: Specifications subject to change without notice. Please check our website for latest information.



4. Schematic:



5. General Specification:

- (a) Operating Temp.: -40°C to +85°C (including self-temperature rise)
- (b) Storage Temp.: -40°C to +85°C (product without taping)
- (c) Humidity Range: 85 ± 2% RH
- (d) Hi- Pot Resistance Test: 1500 VAC for 1 minute
- (e) Storage condition (component in its packaging)
 - i) Temperature: less than 40°C
 - ii) Humidity: 60% RH

6. Electrical Characteristics:

Part Number	Insertion Loss (dB Max.)	Return Loss (dB Min.)					Cross Talk (dB Min.)	DCMR (dB Min.)	
		1~30MHz	40MHz	50MHz	60~80MHz	100MHz		1~60MHz	60~100MHz
SLT161040G241P1B8	-1.1	-18	-14.4	-13.1	-12	-10	-35	-35	-30

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7. Soldering:

Mildly activated rosin fluxes are preferred. Our terminations are suitable for all re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

7-1 Solder Re-flow:

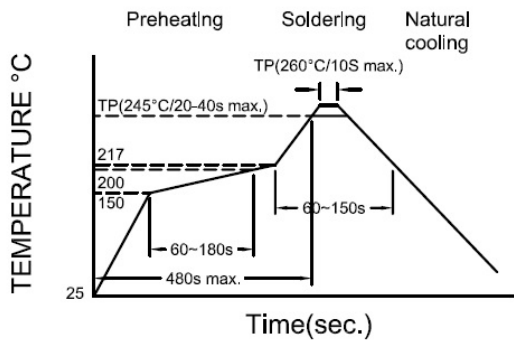
Recommended temperature profiles for re-flow soldering in Figure 1.

7-2 Soldering Iron (Figure 2):

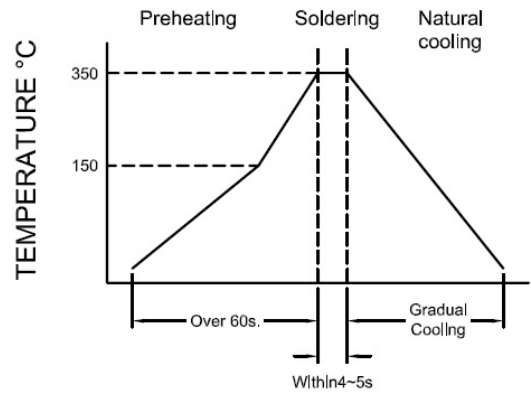
Products attachment with soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

Note :

- a) Preheat circuit and products to 150°C.
- b) 355°C tip temperature (Max.)
- c) 1.0mm tip diameter (Max.)
- d) Use a 20 watt soldering iron with tip diameter of 1.0mm
- e) Limit soldering time to 4~5 secs.



Reflow times: 3 times max
Fig.1



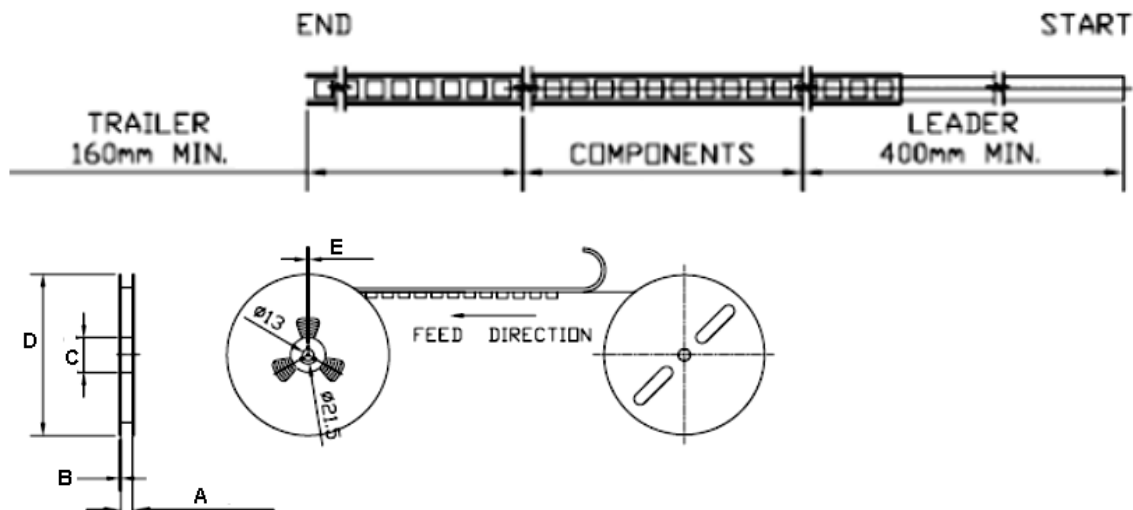
Iron Soldering times: 1 times max
Fig.2

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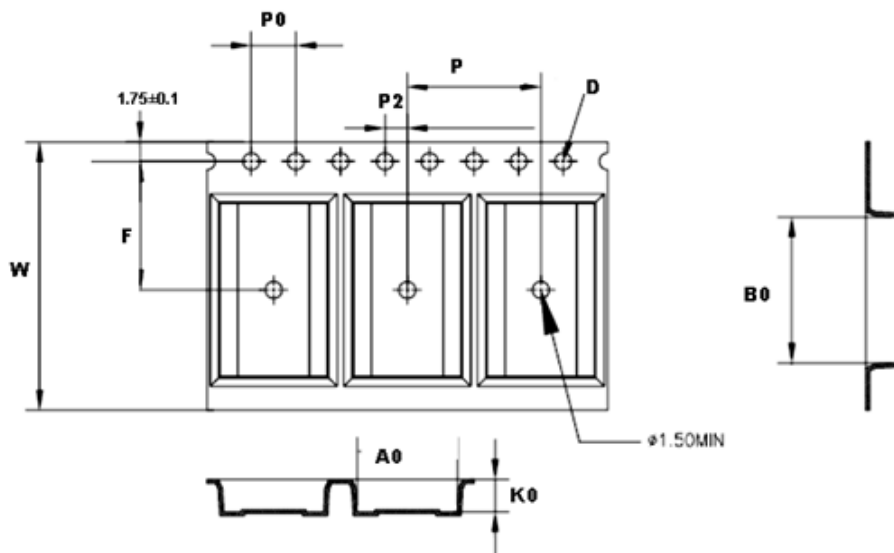
8. Packaging Information:

8-1 Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)
SLT161040G241P1B8	33.5±2.0	2.0±0.15	Ø100	Ø330±2	2.5

8-2 Tape Dimension



Series	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	Po(mm)	P2(mm)	W(mm)	F(mm)	D(mm)
SLT161040G241P1B8	16.8±0.1	10.6±0.1	4.9±0.1	16.0±0.1	4.0±0.1	2.0±0.1	32±0.3	14.2±0.1	1.5±0.1

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8-3 Packaging Quantity

SLT	161040G241P1B8
Chip / Reel	800

Application Notice:

1. Storage Conditions:

To maintain the solderability of terminal electrodes:

- a) Recommended products should be used within 12 months from the time of delivery.
- b) The packaging material should be kept where no chlorine or sulfur exists in the air.

2. Transportation:

- a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- b) Vacuum pick up is strongly recommended for individual components.
- c) Bulk handling should ensure that abrasion and mechanical shock are minimized.

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